



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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NOTES:

MATERIALS

- FERRULE: COPPER ALLOY PER ASTM B139-95
- INSULATION SLEEVE: HEAT-SHRINKABLE, TRANSPARENT BLUE, RADIATION CROSS-LINKED MODIFIED POLYVINYLDENE FLUORIDE.
- SOLDER PERFORM WITH FLUX:
SOLDER: TYPE Sn63 PER ANSI-J-STD-006.
FLUX: TYPE ROM1 PER ANSI-J-STD-004.
- SHIELD: SOLDER IMPREGNATED, FLUX COATED, TIN PLATED COPPER BRAID.
SOLDER: TYPE Sn63 PER ANSI-J-STD-006.
FLUX: TYPE ROM1 PER ANSI-J-STD-004.
- FINISH:
A) FERRULE CADMIUM PLATED IN ACCORDANCE WITH QQ-P-416. OVER A SUITABLE UNDERPLATE.
- INSTALLATION: SEE RAYCHEM INSTALLATION PROCEDURE RPIP-652-35.
- PACKAGING: ONE SPIGOT AND ONE SOLDER SHIELD PER BAG. 10 BAGS IN A BOX.

8 THE VALUES TABLE GIVES GEOMETRICAL GUIDE LINES. HOWEVER PLATING, SHAPE, DIAMETER OF CABLES CAN BE VARY AND AN INSTALLATION MUST BE DONE TO GUARANTEE PROPER RESULT.

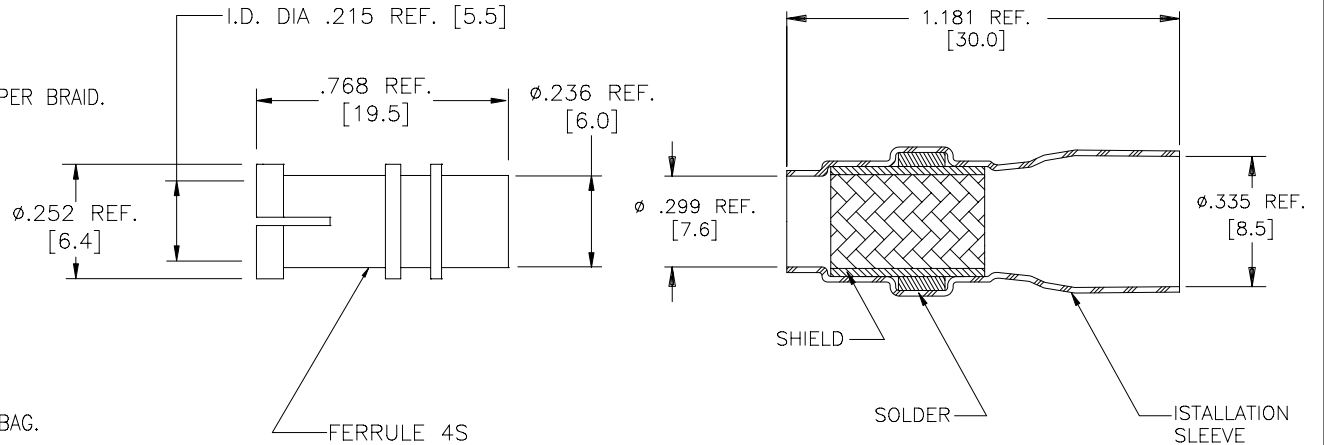
Ø D OUTSIDE DIA OF JACKETS.		Ø E OUTSIDE DIA OF BRAIDS.		Ø F MAX. OUTSIDE DIA OF WIRES.
MIN.	MAX.	MIN.	MAX.	
.140	.315	.071	.236	.201
[3.55]	[8.0]	[1.8]	[6.0]	[5.1]

MAXIMUM QTY. OF BRAIDS: 4

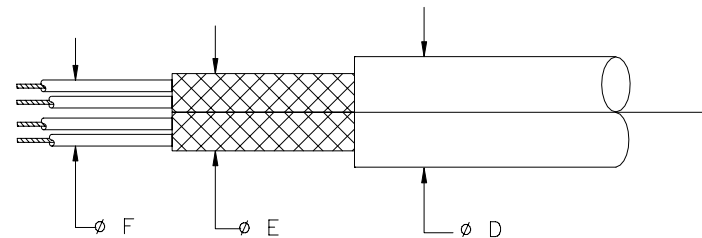
8

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REVISIONS			
LTR	DESCRIPTION	DATE	APPROVED
D	DRAWING HAS BEEN CONVERTED FROM FRENCH PER T-30412	12/10/2001	M.HIGGY



APPLICATIONS



SPECIFICATION CONTROL DRAWING

<p>UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES. METRIC DIMENSIONS ARE IN BRACKETS.</p> <p>DECIMALS .XXX ± .XX ± ANGLES .X ± WEIGHT:</p>	DRAWN	ZS.ORBAN	11/30/2001	<p>tyco Electronics/Raychem</p> <p>WIRE AND HARNESSING PRODUCTS 307 CONSTITUTION DRIVE MENLO PARK, CALIFORNIA 94025</p>	
	CHECKED				
	APPROVED	M.HIGGY	11/30/2001	<p>TITLE</p> <p>SPIGOT LARGE SIZE WITH SOLDER SHIELD FOR MULTIPOINT BACKHELL</p>	
	RPN:				
	CAD NAME	T30412.DWG			
	THIRD ANGLE PROJECTION				
	SIZE	C	CODE IDENT. NO.	06090	DWG. NO.
				ECA-0030	REV D
	DO NOT SCALE THIS DRAWING				SHEET 1 OF 1